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(54) POSITIVE RESIST COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a positive resist composition suitable for the use of an exposure light source at ≤250 nm wavelength, in particular, F2 excimer laser light (at 157 nm), and specifically, to provide a positive resist composition showing sufficient transmitting property when a light source at 157 nm is used, having improved performance such as solubility in a solvent, the occurrence of striation, coating uniformity, line edge roughness, dissolution contrast.

SOLUTION: The positive resist composition contains: (A) a resin containing a fluorine atom and having a group which is decomposed by the effect of a specified acid to increase the solubility with an alkaline developing solution; and a compound (B) which generates an acid by irradiation with active rays or radiation.

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